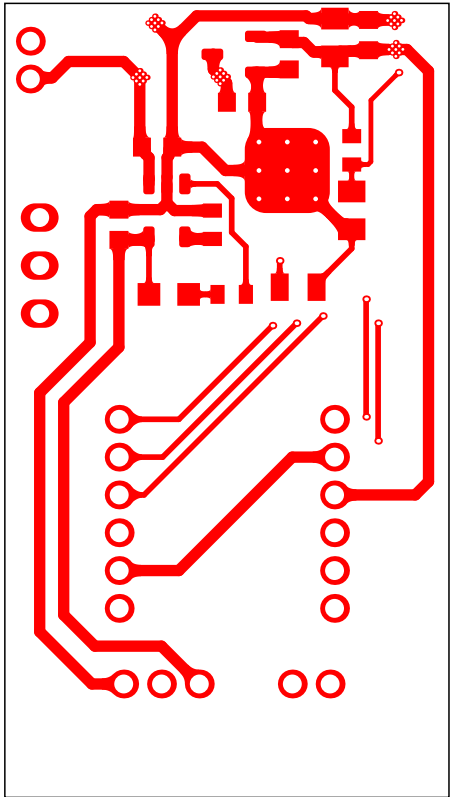
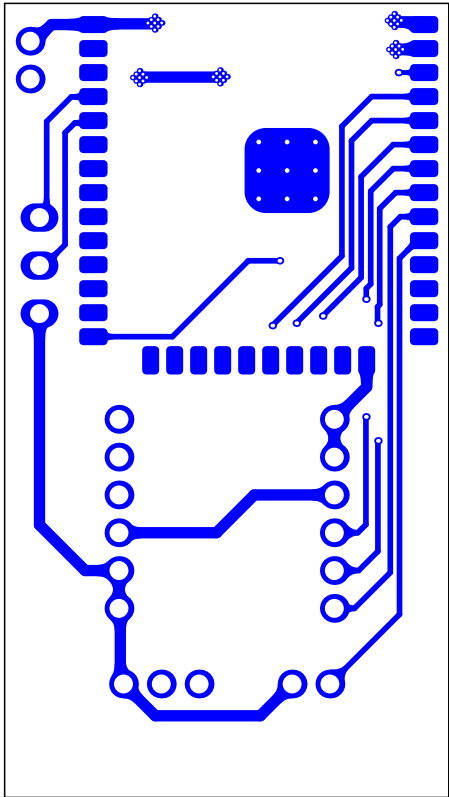


# Motherboard Bracelet

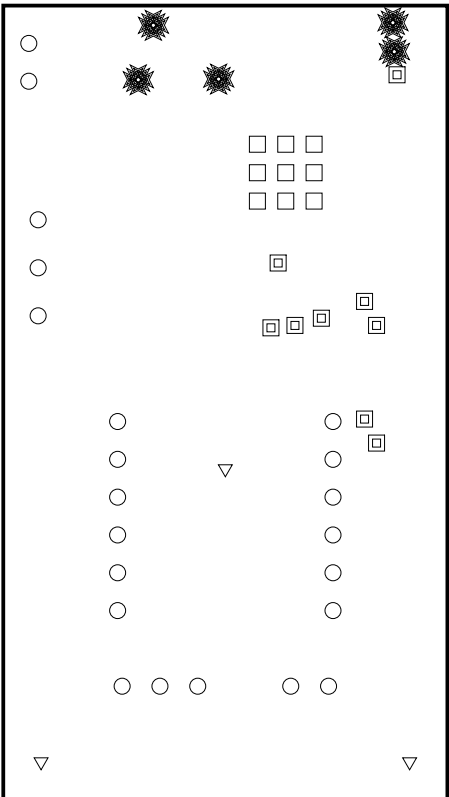
Top Layer (Scale 2.5:1)



Bottom Layer (Scale 2.5:1)



Drill Drawing View (Scale 2.5:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
⌘	45	0.15mm	Plated	
⊞	9	0.20mm	Plated	
□	9	0.25mm	Plated	
○	22	1.00mm	Plated	
▽	3	2.50mm	Non-Plated	
	88 Total			

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
Core		1.50mm	Core-043	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.59mm					



**WF TECNOLOGIA**  
Natan Figueiredo  
+55 41 99558-4388  
[eng.figueiredo@gmail.com](mailto:eng.figueiredo@gmail.com)

Projeto	Motherboard Bracelet		
Elaboração	Roger	Aprovação	Marlio
Código		Revisão	R01
		Folha	1/1
Data	04/11/2024	Horário	23:34
		Tamanho	A3
Arquivo	E:\WF_Tecnologia\Roger_Lakoski_Mestrado\RL_Motherboard_Bracelet\Motherboard_Bracelet_Fabrication.PCBDwf		

Revisão	Data	Responsável	Histórico
R00	17/02/202	Natan MF	=HIST01
R01	02/11/202	Natan MF	=HIST02
			=HIST03
			=HIST04